



Material Content Data Sheet



Sales Product Name		BSZ088N03LS G		Issued		29. August 2013		
MA#		MA000896762						
Package		PG-TSDSON-8-21		Weight*		36.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.804	2.22	2.22	22241	22241
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		65	
	non noble metal	zinc	7440-66-6	0.009	0.03		262	
	non noble metal	iron	7439-89-6	0.189	0.52		5239	
wire	non noble metal	copper	7440-50-8	7.689	21.27	21.83	212718	218284
	noble metal	gold	7440-57-5	0.084	0.23	0.23	2319	2319
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1032
	plastics	epoxy resin	-	1.921	5.31		53139	
	inorganic material	silicondioxide	60676-86-0	16.690	46.20	51.61	461739	515910
leadfinish	non noble metal	tin	7440-31-5	0.370	1.02	1.02	10238	10238
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2235	2235
solder	non noble metal	tin	7440-31-5	0.054	0.15		1506	
	non noble metal	lead	7439-92-1	1.034	2.86	3.01	28605	30111
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		33	
	non noble metal	zinc	7440-66-6	0.005	0.01		130	
	non noble metal	iron	7439-89-6	0.094	0.26		2600	
heat sink CLIP	non noble metal	copper	7440-50-8	3.816	10.56	10.83	105570	108333
	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		108	
	non noble metal	iron	7439-89-6	0.078	0.22		2168	
	non noble metal	copper	7440-50-8	3.182	8.80	9.03	88026	90329
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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